NSR2030QMUTWG

2A, 30V Schottky Full Bridge

These full bridge Schottky barrier diodes are designed for the rectification of the high speed signal of wireless charging. The NSR2030QMUTWG has a very low forward voltage that will reduce conduction loss. It is housed in a UDFN 3.5 x 3.5 x 0.5 mm package that is ideal for space constrained wireless applications.

Features

- Extremely Fast Switching Speed
- Low Forward Voltage -0.54 V (Typ) @ I_F = 2 A
- These Devices are Pb-Free, Halogen Free and are RoHS Compliant

Typical Applications

• Low Voltage Full Bridge Rectification & Wireless Charging

MAXIMUM RATINGS (T_J = 125°C unless otherwise noted) (Note 1)

Rating	Symbol	Value	Unit
Reverse Voltage	V _R	30	V
Forward Current (DC)	١ _F	2.0	А
Forward Current Surge Peak (60 Hz, 1 cycle)	I _{FSM}	12.5	A
Non-Repetitive Peak Forward Current (Square Wave, $T_J = 25^{\circ}C$ prior to surge) $t = 1 \ \mu s$ $t = 1 \ ms$ $t = 1 \ s$	I _{FSM}	40 10 3.0	A

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. 1. All specifications pertain to a single diode.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit			
Total Device Dissipation FR-5 Board $T_A = 25^{\circ}C$	P _D (Note 2)	2.08	W			
Derate above 25°C		20.8	mW/°C			
Thermal Resistance Junction to Ambient	R _{θJA} (Note 2)	48	°C/W			
Total Device Dissipation FR-5 Board $T_A = 25^{\circ}C$	P _D (Note 3)	0.75	W			
Derate above 25°C		7.6	mW/°C			
Thermal Resistance Junction to Ambient	R _{0JA} (Note 3)	132	°C/W			
Total Device Dissipation FR-5 Board $T_A = 25^{\circ}C$	P _D (Note 4)	0.87	W			
Derate above 25°C		8.8	mW/°C			
Thermal Resistance Junction to Ambient	R _{0JA} (Note 4)	114	°C/W			
Junction Temperature	TJ	+125	°C			
Storage Temperature Range	T _{stg}	–55 to +150	°C			
	-					

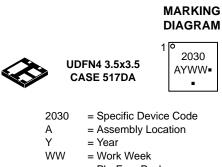
2. 4 Layer JEDEC JESD51.7 FR-4 @ 10 mm², 1 oz. copper trace, still air.

Single Layer JEDEC JESD51.3 FR-4 @ 100 mm², 1 oz. copper trace, still air.
Single Layer JEDEC JESD51.3 FR-4 @ 100 mm², 2 oz. copper trace, still air.



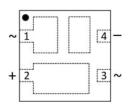
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= Pb-Free Package (Note: Microdot may be in either location)

PIN CONNECTIONS



DEVICE SCHEMATIC



ORDERING INFORMATION

Device	Package	Shipping†
NSR2030QMUTWG	UDFN4 (Pb-Free)	3000 / Tape & Reel

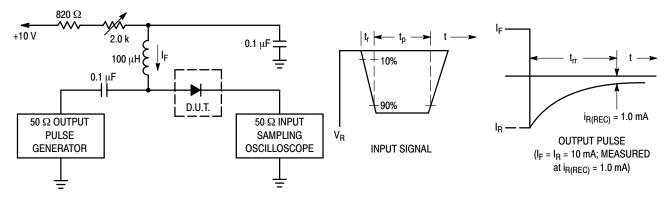
+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

NSR2030QMUTWG

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted) (Note 5)

Characteristic	Symbol	Min	Тур	Max	Unit
Reverse Breakdown Voltage (I _R = 1.0 mA)	V _(BR)	30	-	-	V
Reverse Leakage (V _R = 30 V)	I _R	-	5.0	20	μΑ
Forward Voltage (I _F = 0.5 A)	V _F	-	0.41	0.455	V
Forward Voltage (I _F = 1.0 A)	V _F	-	0.46	0.55	V
Forward Voltage ($I_F = 2.0 \text{ A}$)	V _F	-	0.54	0.65	V
Reverse Recovery Time ($I_F = I_R = 10 \text{ mA}, I_{R(REC)} = 1.0 \text{ mA}$)	t _{rr}	-	34	-	ns
Input Capacitance (pins 1 to 3) ($V_R = 1.0 V$, f = 1.0 MHz)	C _T	-	102	-	pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 5. All specifications pertain to a single diode.



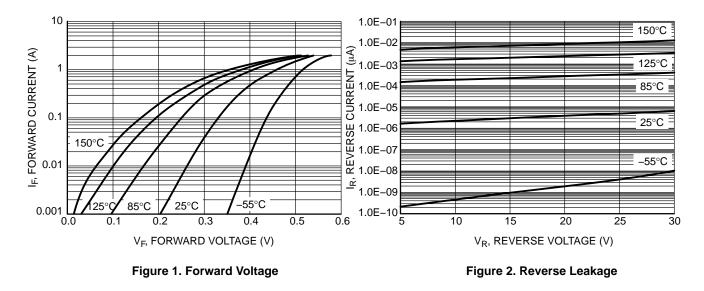
Notes: 1. A 2.0 k Ω variable resistor adjusted for a Forward Current (I_F) of 10 mA. 2. Input pulse is adjusted so $I_{R(\text{peak})}$ is equal to 10 mA.

3. t_p » t_{rr}

Figure 1. Recovery Time Equivalent Test Circuit

NSR2030QMUTWG

TYPICAL CHARACTERISTICS



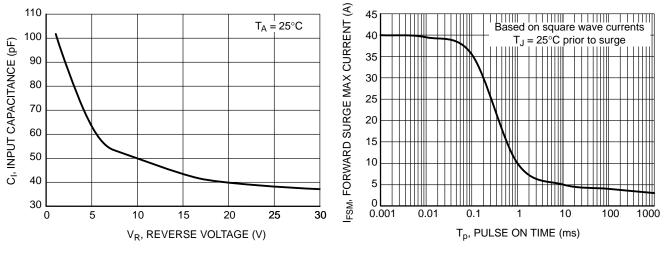
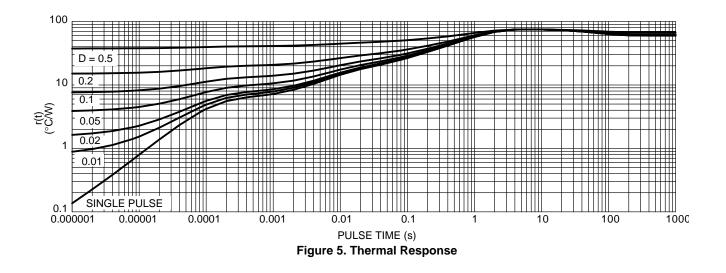


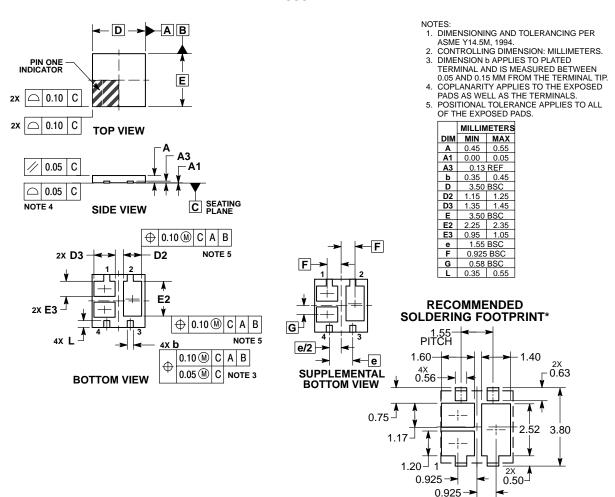
Figure 3. Input Capacitance

Figure 4. Forward Surge Current



PACKAGE DIMENSIONS

UDFN4 3.5x3.5, 1.55P CASE 517DA ISSUE A



DIMENSIONS: MILLIMETERS

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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